



PRODUCT DATA SHEET



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Datasheet



Resources



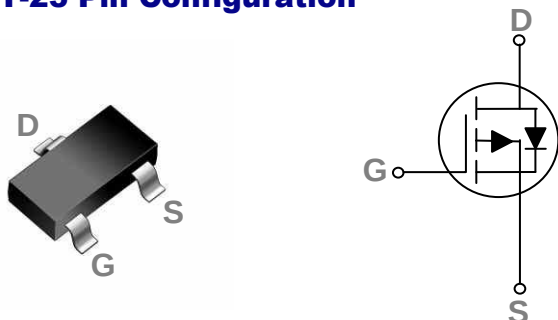
Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT-23 Pin Configuration



BVDSS	RDS(ON)	ID
-20V	70mΩ	-3.3A

Features

- -20V, -3.3A, $R_{DS(ON)} = 70m\Omega @ V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-3.3	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-2.1	A
I_{DM}	Drain Current – Pulsed ¹	-13.2	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	1.56	W
	Power Dissipation – Derate above 25°C	0.012	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.01	---	$V/^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-20V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-16V$, $V_{GS}=0V$, $T_J=125^{\circ}\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$	---	---	± 10	μA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V$, $I_D=-3A$	---	70	85	$m\Omega$
		$V_{GS}=-2.5V$, $I_D=-2A$	---	95	120	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3	---	$mV/^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=-10V$, $I_S=-1A$	---	2.2	---	S

Dynamic and switching Characteristics

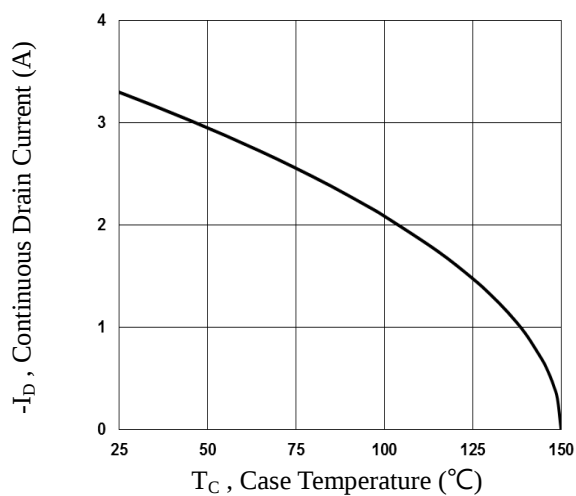
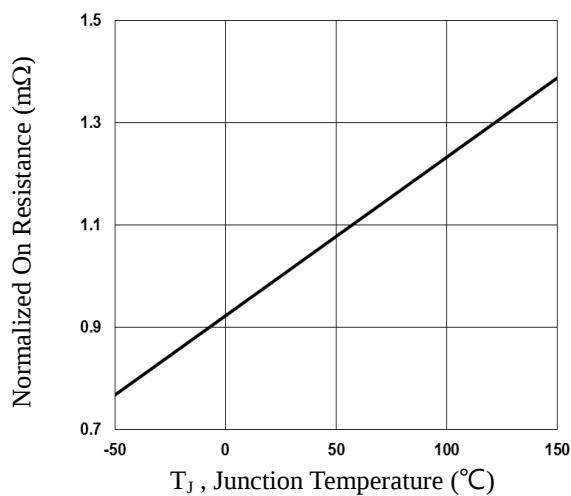
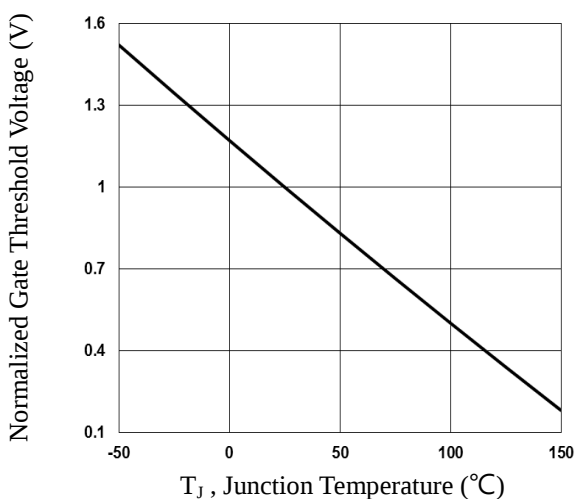
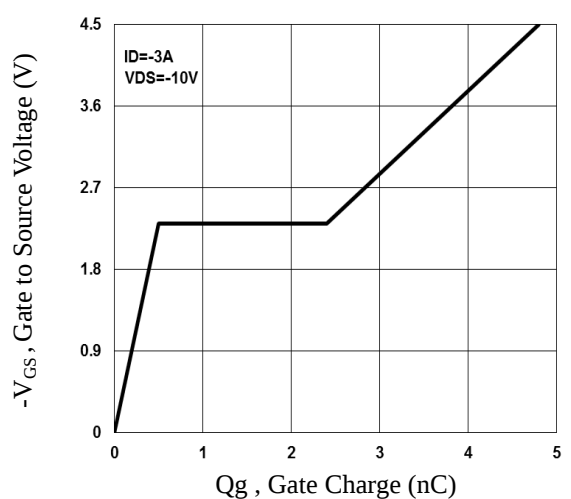
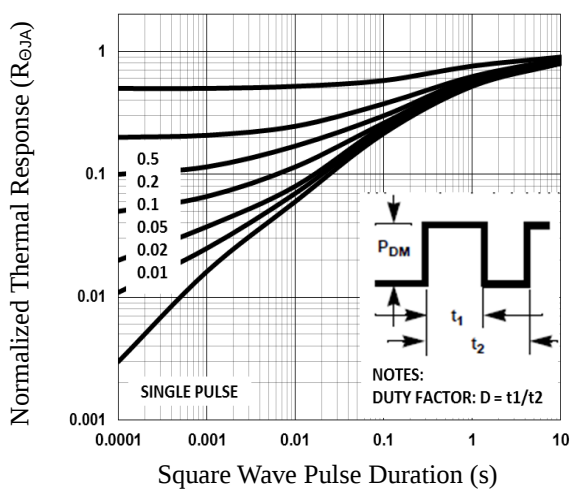
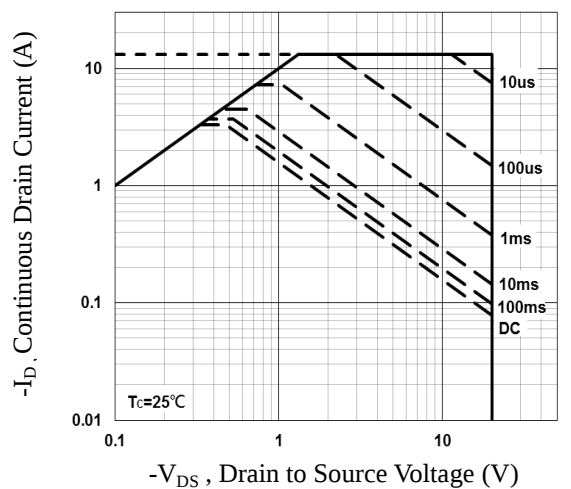
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-10V$, $V_{GS}=-4.5V$, $I_D=-3A$	---	4.8		nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	0.5		
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	1.9		
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-10V$, $V_{GS}=-4.5V$, $R_G=25\Omega$ $I_D=-1A$	---	3.5		nS
T_r	Rise Time ^{2, 3}		---	12.6		
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	32.6		
T_f	Fall Time ^{2, 3}		---	8.4		
C_{iss}	Input Capacitance	$V_{DS}=-15V$, $V_{GS}=0V$, $F=1\text{MHz}$	---	350		pF
C_{oss}	Output Capacitance		---	65		
C_{rss}	Reverse Transfer Capacitance		---	50		

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	-3.3	A
I_{SM}	Pulsed Source Current		---	---	-13.2	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=-1A$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized $R_{DS(on)}$ vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

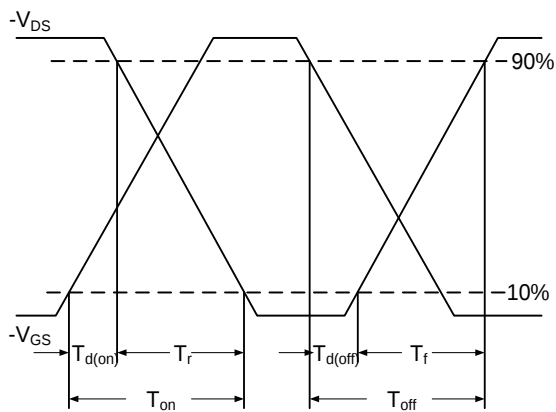


Fig.7 Switching Time Waveform

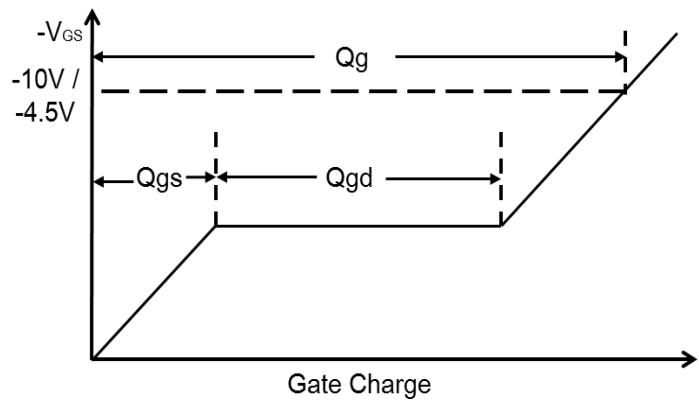
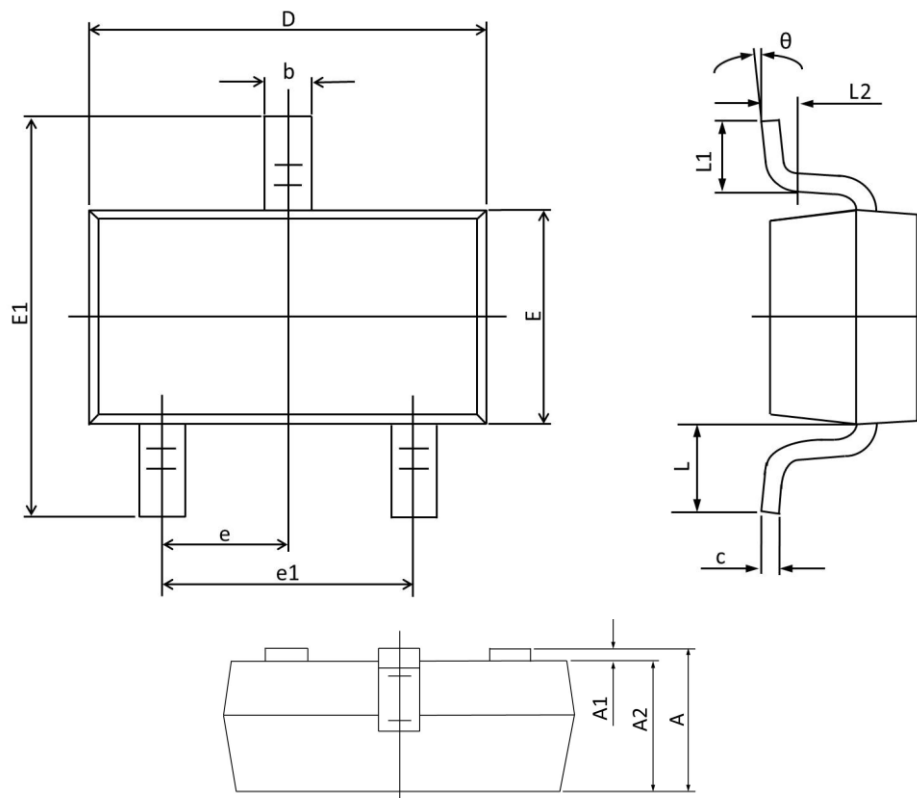


Fig.8 Gate Charge Waveform

SOT-23 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Max	Min	Max	Min
A	1.150	0.900	0.045	0.035
A1	0.100	0.000	0.004	0.000
A2	1.050	0.900	0.041	0.035
b	0.500	0.300	0.020	0.012
c	0.150	0.080	0.006	0.003
D	3.000	2.800	0.118	0.110
E	1.400	1.200	0.055	0.047
E1	2.550	2.250	0.100	0.089
e	0.95 TYP.		0.037 TYP.	
e1	2.000	1.800	0.079	0.071
L	0.55 REF.		0.022 REF.	
L1	0.500	0.300	0.020	0.012
L2	0.25 TYP.		0.01 TYP.	
θ	8°	0°	8°	0°

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